Microchip Technology - DSPIC33FJ32MC101-I/SS Datasheet

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	16 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, Motor Control PWM, POR, PWM, WDT
Number of I/O	15
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj32mc101-i-ss

3.3 Special MCU Features

The dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 features a 17-bit by 17-bit, single-cycle multiplier that is shared by both the MCU ALU and DSP engine. The multiplier can perform signed, unsigned and mixed-sign multiplication. Using a 17-bit by 17-bit multiplier for 16-bit by 16-bit multiplication not only allows you to perform mixed-sign multiplication, it also achieves accurate results for special operations, such as (-1.0) x (-1.0).

The dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 supports 16/16 and 32/16 divide operations, both fractional and integer. All divide instructions are iterative operations. They must be executed within a REPEAT loop, resulting in a total execution time of 19 instruction cycles. The divide operation can be interrupted during any of those 19 cycles without loss of data.

A 40-bit barrel shifter is used to perform up to a 16-bit left or right shift in a single cycle. The barrel shifter can be used by both MCU and DSP instructions.

FIGURE 3-1: dsPIC33FJ16(GP/MC)101/102 AND dsPIC33FJ32(GP/MC)101/102/104 CPU CORE BLOCK DIAGRAM

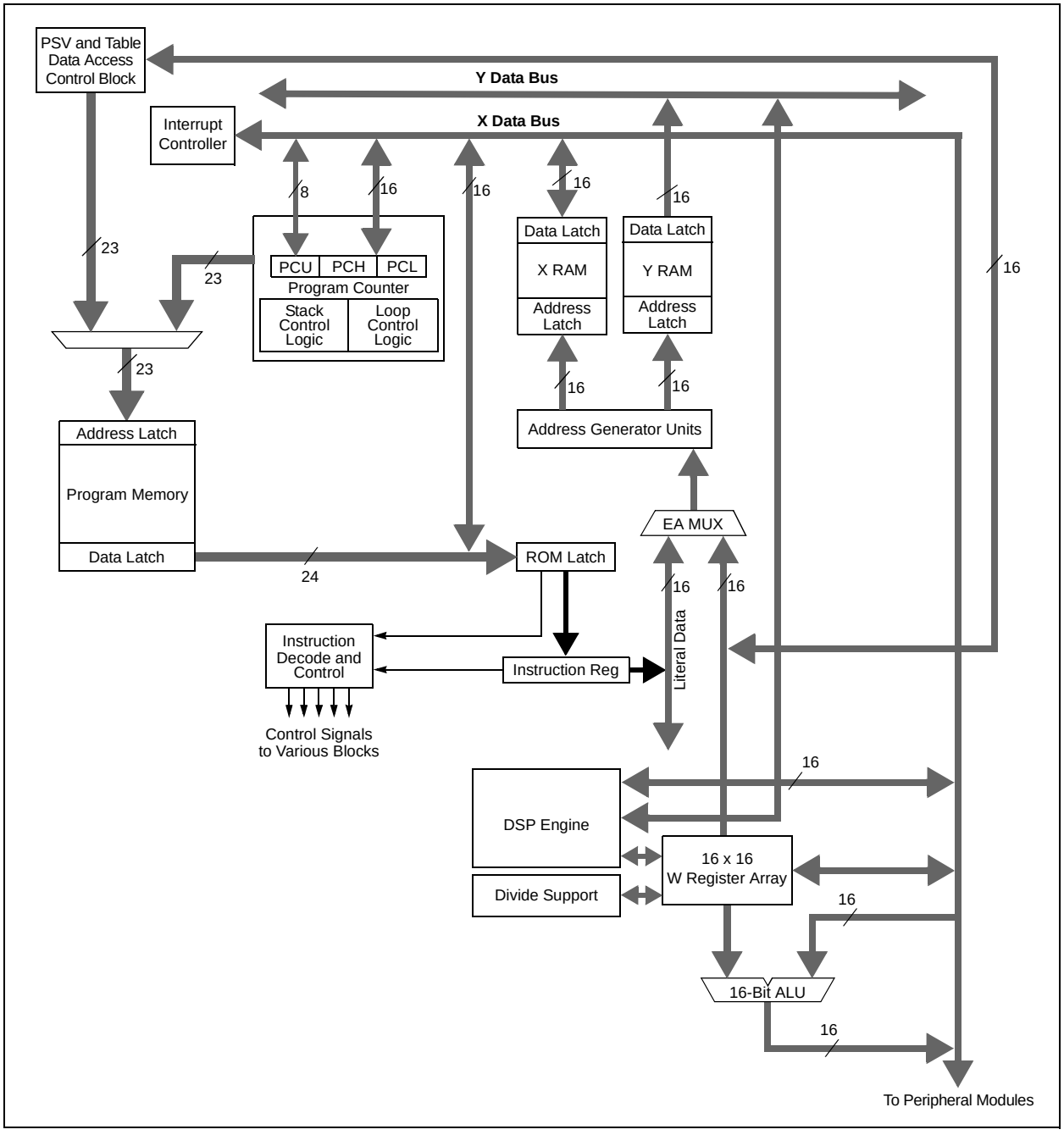


TABLE 7-2: TRAP VECTORS

Vector Number	IVT Address	AIVT Address	Trap Source
0	0x000004	0x000104	Reserved
1	0x000006	0x000106	Oscillator Failure
2	0x000008	0x000108	Address Error
3	0x00000A	0x00010A	Stack Error
4	0x00000C	0x00010C	Math Error
5	0x00000E	0x00010E	Reserved
6	0x000010	0x000110	Reserved
7	0x000012	0x000112	Reserved

7.3 Interrupt Control and Status Registers

The dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices implement a total of 26 registers for the interrupt controller:

- INTCON1
- INTCON2
- IFSx
- IECx
- IPCx
- INTTREG

7.3.1 INTCON1 AND INTCON2

Global interrupt functions are controlled from INTCON1 and INTCON2. INTCON1 contains the Interrupt Nesting Disable (NSTDIS) bit as well as the control and status flags for the processor trap sources. The INTCON2 register controls the external interrupt request signal behavior and the use of the Alternate Interrupt Vector Table.

7.3.2 IFSx Registers

The IFSx registers maintain all of the interrupt request flags. Each source of interrupt has a status bit, which is set by the respective peripherals or external signal and is cleared via software.

7.3.3 IECx Registers

The IECx registers maintain all of the interrupt enable bits. These control bits are used to individually enable interrupts from the peripherals or external signals.

7.3.4 IPCx Registers

The IPCx registers are used to set the Interrupt Priority Level (IPL) for each source of interrupt. Each user interrupt source can be assigned to one of eight priority levels.

7.3.5 INTTREG

The INTTREG register contains the associated interrupt vector number and the new CPU Interrupt Priority Level, which are latched into Vector Number (VECNUM<6:0>) and Interrupt Level (ILR<3:0>) bit fields in the INTTREG register. The new Interrupt Priority Level is the priority of the pending interrupt.

The interrupt sources are assigned to the IFSx, IECx and IPCx registers in the same sequence that they are listed in Table 7-1. For example, the INT0 (External Interrupt 0) is shown as having Vector Number 8 and a natural order priority of 0. Thus, the INT0IF bit is found in IFS0<0>, the INT0IE bit in IEC0<0> and the INT0IPx bits in the first positions of IPC0 (IPC0<2:0>).

7.3.6 STATUS/CONTROL REGISTERS

Although they are not specifically part of the interrupt control hardware, two of the CPU Control registers contain bits that control interrupt functionality.

- The CPU STATUS Register, SR, contains the IPL<2:0> bits (SR<7:5>). These bits indicate the current CPU Interrupt Priority Level. The user application can change the current CPU Interrupt Priority Level by writing to the IPLx bits.
- The CORCON register contains the IPL3 bit which, together with IPL<2:0>, also indicates the current CPU Interrupt Priority Level. IPL3 is a read-only bit so that trap events cannot be masked by the user software.

All Interrupt registers are described in Register 7-1 through Register 7-28 on the following pages.

NOTES:

REGISTER 10-3: RPINR3: PERIPHERAL PIN SELECT INPUT REGISTER 3

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	T3CKR4	T3CKR3	T3CKR2	T3CKR1	T3CKR0
bit 15							bit 8

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	T2CKR4	T2CKR3	T2CKR2	T2CKR1	T2CKR0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12-8 **T3CKR<4:0>:** Assign Timer3 External Clock (T3CK) to the Corresponding RPn Pin bits

11111 = Input tied to Vss
11110 = Reserved
.
.
.
11010 = Reserved
11001 = Input tied to RP25
.
.
.
00001 = Input tied to RP1
00000 = Input tied to RP0

bit 7-5 **Unimplemented:** Read as ‘0’

bit 4-0 **T2CKR<4:0>:** Assign Timer2 External Clock (T2CK) to the Corresponding RPn Pin bits

11111 = Input tied to Vss
11110 = Reserved
.
.
.
11010 = Reserved
11001 = Input tied to RP25
.
.
.
00001 = Input tied to RP1
00000 = Input tied to RP0

REGISTER 10-21: RPOR10: PERIPHERAL PIN SELECT OUTPUT REGISTER 10

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	RP21R<4:0>(1)				
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	RP20R<4:0>(1)				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **RP21R<4:0>:** Peripheral Output Function is Assigned to RP21 Output Pin bits(1)
(see Table 10-2 for peripheral function numbers)

bit 7-5 **Unimplemented:** Read as '0'

bit 4-0 **RP20R<4:0>:** Peripheral Output Function is Assigned to RP20 Output Pin bits(1)
(see Table 10-2 for peripheral function numbers)

Note 1: These bits are available in dsPIC33FJ32(GP/MC)104 devices only.

REGISTER 10-22: RPOR11: PERIPHERAL PIN SELECT OUTPUT REGISTER 11

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	RP23R<4:0>(1)				
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	RP22R<4:0>(1)				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **RP23R<4:0>:** Peripheral Output Function is Assigned to RP23 Output Pin bits(1)
(see Table 10-2 for peripheral function numbers)

bit 7-5 **Unimplemented:** Read as '0'

bit 4-0 **RP22R<4:0>:** Peripheral Output Function is Assigned to RP22 Output Pin bits(1)
(see Table 10-2 for peripheral function numbers)

Note 1: These bits are available in dsPIC33FJ32(GP/MC)104 devices only.

REGISTER 20-4: CMxMSKCON: COMPARATOR x MASK GATING CONTROL REGISTER (CONTINUED)

bit 3 **ABEN:** AND Gate A1 B Input Inverted Enable bit
1 = MBI is connected to AND gate
0 = MBI is not connected to AND gate

bit 2 **ABNEN:** AND Gate A1 B Input Inverted Enable bit
1 = Inverted MBI is connected to AND gate
0 = Inverted MBI is not connected to AND gate

bit 1 **AAEN:** AND Gate A1 A Input Enable bit
1 = MAI is connected to AND gate
0 = MAI is not connected to AND gate

bit 0 **AANEN:** AND Gate A1 A Input Inverted Enable bit
1 = Inverted MAI is connected to AND gate
0 = Inverted MAI is not connected to AND gate

REGISTER 21-1: RCFGCAL: RTCC CALIBRATION AND CONFIGURATION REGISTER(1) (CONTINUED)

bit 7-0 **CAL<7:0>:** RTC Drift Calibration bits

01111111 = Maximum positive adjustment; adds 508 RTC clock pulses every one minute
•
•
•
00000001 = Minimum positive adjustment; adds 4 RTC clock pulses every one minute
00000000 = No adjustment
11111111 = Minimum negative adjustment; subtracts 4 RTC clock pulses every one minute
•
•
•
10000000 = Maximum negative adjustment; subtracts 512 RTC clock pulses every one minute

Note 1: The RCFGCAL register is only affected by a POR.

2: A write to the RTCEN bit is only allowed when RTCWREN = 1.

3: This bit is read-only; it is cleared to '0' on a write to the lower half of the MINSEC register.

REGISTER 21-2: PADCFG1: PAD CONFIGURATION CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	U-0
—	—	—	—	—	—	RTSECSEL(1)	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-2 **Unimplemented:** Read as ‘0’

bit 1 **RTSECSEL:** RTCC Seconds Clock Output Select bit(1)
1 = RTCC seconds clock is selected for the RTCC pin
0 = RTCC alarm pulse is selected for the RTCC pin

bit 0 **Unimplemented:** Read as ‘0’

Note 1: To enable the actual RTCC output, the RTCOE (RCFGCAL<10>) bit needs to be set.

REGISTER 21-4: RTCVAL (WHEN RTCPTR<1:0> = 11): RTCC YEAR VALUE REGISTER(1)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
YRTEN3	YRTEN2	YRTEN1	YRTEN0	YRONE3	YRONE2	YRONE1	YRONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7-4 **YRTEN<3:0>:** Binary Coded Decimal Value of Year's Tens Digit bits
Contains a value from 0 to 9.

bit 3-0 **YRONE<3:0>:** Binary Coded Decimal Value of Year's Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to this register is only allowed when RTCWREN = 1.

REGISTER 21-5: RTCVAL (WHEN RTCPTR<1:0> = 10): RTCC MONTH AND DAY VALUE REGISTER(1)

U-0	U-0	U-0	R-x	R-x	R-x	R-x	R-x
—	—	—	MTHTEN0	MTHONE3	MTHONE2	MTHONE1	MTHONE0
bit 15							bit 8

U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	DAYTEN1	DAYTEN0	DAYONE3	DAYONE2	DAYONE1	DAYONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12 **MTHTEN0:** Binary Coded Decimal Value of Month's Tens Digit bit
Contains a value of 0 or 1.

bit 11-8 **MTHONE<3:0>:** Binary Coded Decimal Value of Month's Ones Digit bits
Contains a value from 0 to 9.

bit 7-6 **Unimplemented:** Read as '0'

bit 5-4 **DAYTEN<1:0>:** Binary Coded Decimal Value of Day's Tens Digit bits
Contains a value from 0 to 3.

bit 3-0 **DAYONE<3:0>:** Binary Coded Decimal Value of Day's Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to this register is only allowed when RTCWREN = 1.

TABLE 26-10: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
DI10		I/O Pins	VSS	—	0.2 VDD	V	
DI15		$\overline{\text{MCLR}}$	VSS	—	0.2 VDD	V	
DI18		I/O Pins with SDAx, SCLx	VSS	—	0.3 VDD	V	SMBus disabled
DI19		I/O Pins with SDAx, SCLx	VSS	—	0.8	V	SMBus enabled
	VIH	**Input High Voltage**					
DI20		I/O Pins Not 5V Tolerant(4) I/O Pins 5V Tolerant(4)	0.7 VDD 0.7 VDD	— —	VDD 5.5	V V	
DI28		SDAx, SCLx	0.7 VDD	—	5.5	V	SMBus disabled
DI29		SDAx, SCLx	2.1	—	5.5	V	SMBus enabled
	ICNPU	**CNx Pull-up Current**					
DI30			50	250	450	µA	VDD = 3.3V, VPIN = VSS
	IIL	**Input Leakage Current(2,3)**					
DI50		I/O Pins 5V Tolerant(4)	—	—	±2	µA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI51		I/O Pins Not 5V Tolerant(4)	—	—	±1	µA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, -40°C ≤ TA ≤ +85°C
DI51a		I/O Pins Not 5V Tolerant(4)	—	—	±2	µA	Shared with external reference pins, -40°C ≤ TA ≤ +85°C
DI51b		I/O Pins Not 5V Tolerant(4)	—	—	±3.5	µA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, -40°C ≤ TA ≤ +125°C
DI51c		I/O Pins Not 5V Tolerant(4)	—	—	±8	µA	Analog pins shared with external reference pins, -40°C ≤ TA ≤ +125°C
DI55		$\overline{\text{MCLR}}$	—	—	±2	µA	VSS ≤ VPIN ≤ VDD
DI56		OSC1	—	—	±2	µA	VSS ≤ VPIN ≤ VDD, XT and HS modes

Note 1: Data in “Typ” column is at 3.3V, +25°C unless otherwise stated.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: See the **“Pin Diagrams”** section for the 5V tolerant I/O pins.

5: VIL source < (VSS – 0.3). Characterized but not tested.

6: Non-5V tolerant pins, VIH source > (VDD + 0.3), 5V tolerant pins, VIH source > 5.5V. Characterized but not tested.

7: Digital 5V tolerant pins cannot tolerate any “positive” input injection current from input sources > 5.5V.

8: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

9: Any number and/or combination of I/O pins, not excluded under IICL or IICH conditions, are permitted provided the mathematical “absolute instantaneous” sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

TABLE 26-17: PLL CLOCK TIMING SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
OS50	FPLLI	PLL Voltage Controlled Oscillator (VCO) Input Frequency Range(2)	3.0	—	8	MHz	ECPLL and MSPLL modes
OS51	FSYS	On-Chip VCO System Frequency(3)	12	—	32	MHz	
OS52	TLOCK	PLL Start-up Time (Lock Time)(3)	—	—	2	mS	
OS53	DCLK	CLKO Stability (Jitter)(3)	-2	1	+2	%	

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: These parameters are characterized by similarity, but are tested in manufacturing at 7.7 MHz input only.

3: These parameters are characterized by similarity, but are not tested in manufacturing. This specification is based on clock cycle by clock cycle measurements. The effective jitter for individual time bases, or communication clocks used by the user application, are derived from dividing the CLKO stability specification by the square root of "N" (where "N" is equal to FOSC, divided by the peripheral data rate clock). For example, if FOSC = 32 MHz and the SPI bit rate is 5 MHz, the effective jitter of the SPI clock is equal to:

$$\frac{DCLK}{\sqrt{\frac{32}{5}}} = \frac{2\%}{2.53} = 0.79\%$$

TABLE 26-18: AC CHARACTERISTICS: INTERNAL FAST RC (FRC) ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**	
	Internal FRC Accuracy @ 7.37 MHz(1)						
F20a	FRC	-2	±0.25	+2	%	-40°C ≤ TA ≤ -10°C	VDD 3.0-3.6V
F20b	FRC	-1	±0.25	+1	%	-10°C ≤ TA ≤ +85°C	VDD 3.0-3.6V
F20c	FRC	-5	±0.25	+5	%	+85°C ≤ TA ≤ +125°C	VDD 3.0-3.6V

Note 1: Frequency is calibrated at +25°C and 3.3V. TUNx bits may be used to compensate for temperature drift.

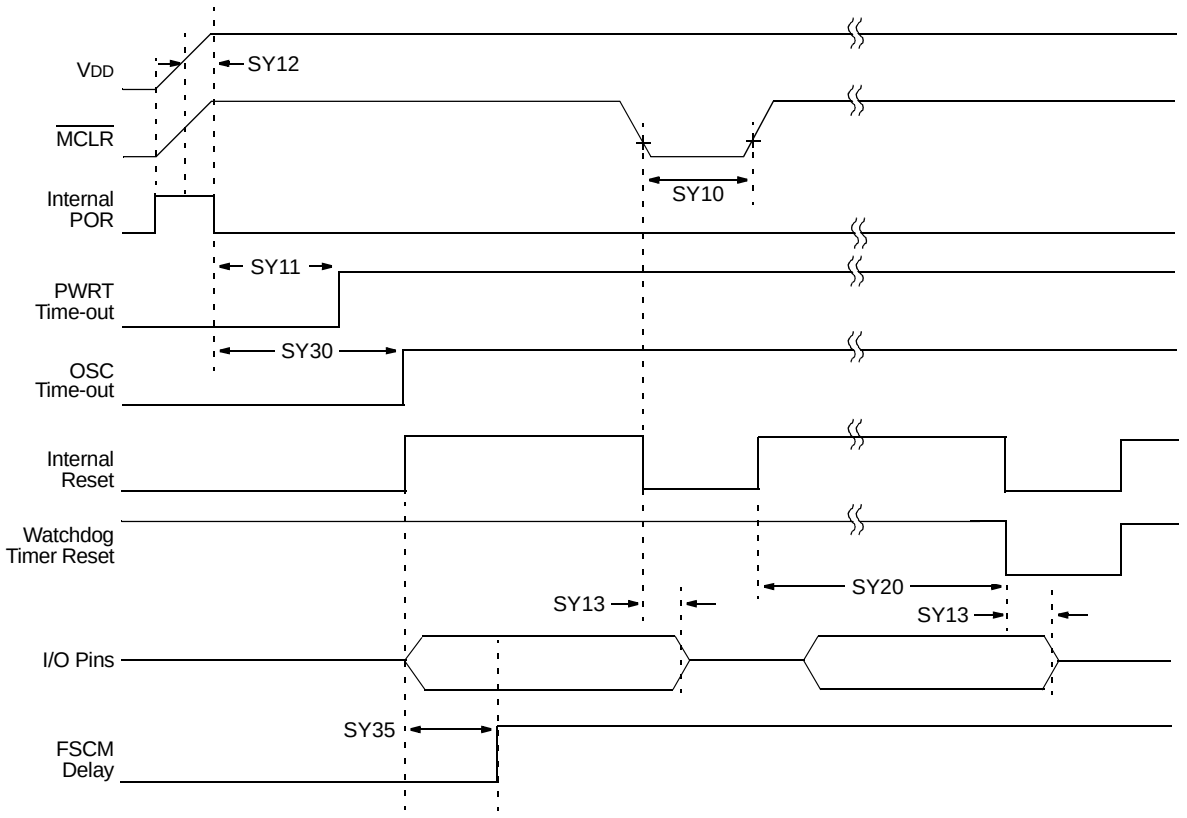
TABLE 26-19: INTERNAL LOW-POWER RC (LPRC) ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**	
	LPRC @ 32.768 kHz(1,2)						
F21a	LPRC	-30	±10	+20	%	-40°C ≤ TA ≤ -10°C	VDD 3.0-3.6V
F21b	LPRC	-20	±10	+30	%	-10°C ≤ TA ≤ +85°C	VDD 3.0-3.6V
F21c	LPRC	-35	±10	+35	%	+85°C ≤ TA ≤ +125°C	VDD 3.0-3.6V

Note 1: Change of LPRC frequency as VDD changes.

2: LPRC accuracy impacts the Watchdog Timer Time-out Period (TWDT1). See **Section 23.4 "Watchdog Timer (WDT)"** for more information.

FIGURE 26-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING CHARACTERISTICS



Note: Refer to Figure 26-1 for load conditions.

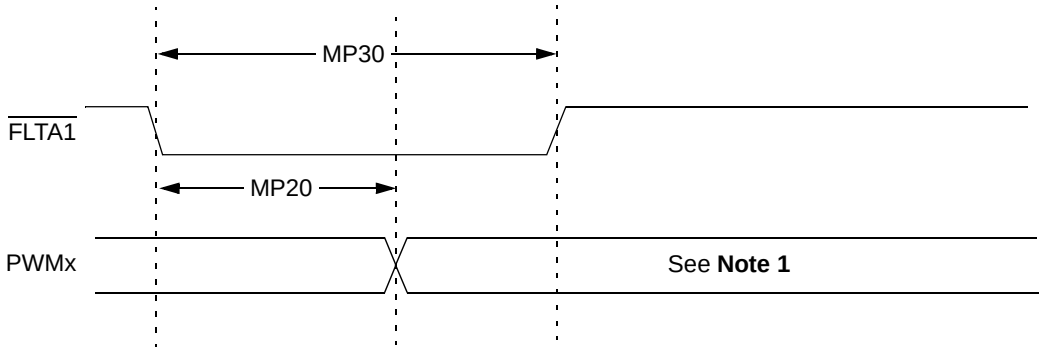
TABLE 26-21: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER AND BROWN-OUT RESET TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symb**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SY10	TMCL	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	µs	
SY11	TPWRT	Power-up Timer Period	—	64	—	ms	
SY12	TPOR	Power-on Reset Delay	3	10	30	µs	
SY13	TIOZ	I/O High-Impedance from $\overline{\text{MCLR}}$ Low or Watchdog Timer Reset	—	—	1.2	µs	
SY20	TWDT1	Watchdog Timer Time-out Period	—	—	—	ms	See **Section 23.4 "Watchdog Timer (WDT)"** and LPRC Parameter F21a (Table 26-19).
SY30	TOST	Oscillator Start-up Time	—	1024 * TOSC	—	—	TOSC = OSC1 period
SY35	TFSCM	Fail-Safe Clock Monitor Delay	—	500	900	µs	

Note 1: These parameters are characterized but are not tested in manufacturing.

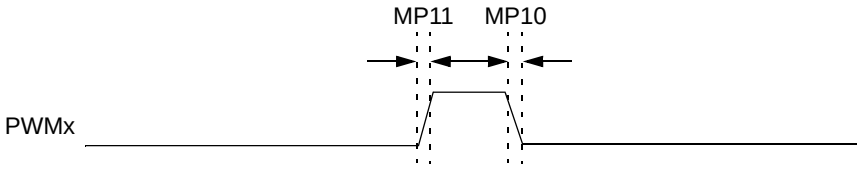
2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

FIGURE 26-9: MOTOR CONTROL PWMx MODULE FAULT TIMING CHARACTERISTICS



Note 1: For the logic state after a Fault, refer to the FAOVxH:FAOVxL bits in the PxFLTACON register.

FIGURE 26-10: MOTOR CONTROL PWMx MODULE TIMING CHARACTERISTICS



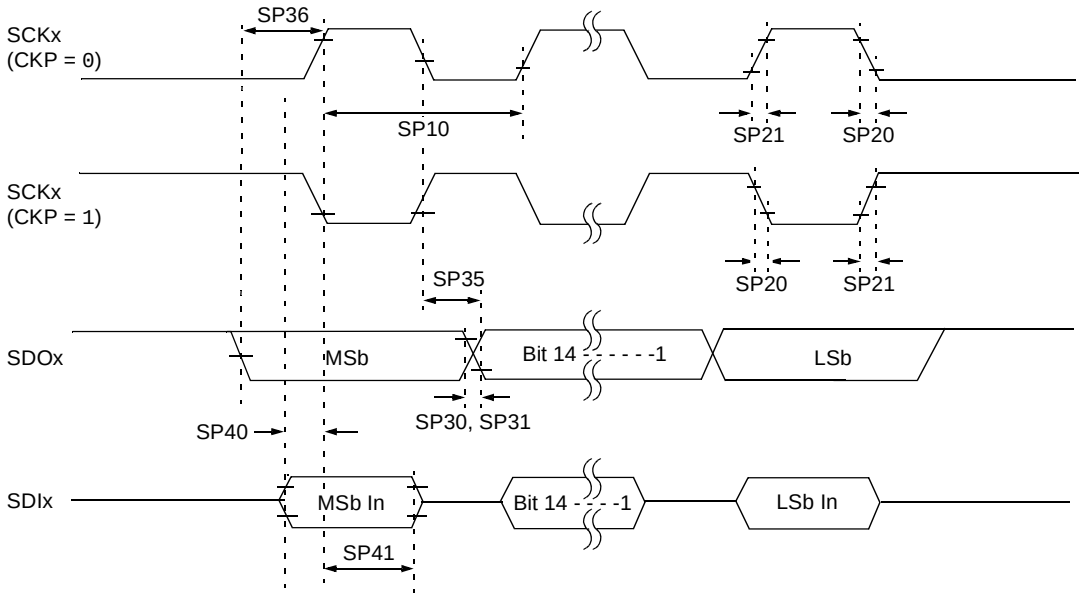
Note: Refer to Figure 26-1 for load conditions.

TABLE 26-28: MOTOR CONTROL PWMx MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
MP10	TFPWM	PWM Output Fall Time	—	—	—	ns	See Parameter DO32
MP11	TRPWM	PWM Output Rise Time	—	—	—	ns	See Parameter DO31
MP20	TFD	Fault Input ↓ to PWM I/O Change	—	—	50	ns	
MP30	TFH	Minimum Pulse Width	50	—	—	ns	

Note 1: These parameters are characterized by similarity, but are not tested in manufacturing.

FIGURE 26-13: SPIx MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING CHARACTERISTICS FOR dsPIC33FJ16(GP/MC)10X



Note: Refer to Figure 26-1 for load conditions.

TABLE 26-31: SPIx MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING REQUIREMENTS FOR dsPIC33FJ16(GP/MC)10X

AC CHARACTERISTICS			Standard Operating Conditions: 2.4V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP10	TscP	Maximum SCKx Frequency	—	—	10	MHz	See **Note 3**
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2sc, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 100 ns. The clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

TABLE 26-45: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic**		**Min(1)**	**Max**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM11	THI:SCL	Clock High Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	
			400 kHz mode	100	—	ns	
			1 MHz mode(2)	40	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	µs	
			400 kHz mode	0	0.9	µs	
			1 MHz mode(2)	0.2	—	µs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	After this period the first clock pulse is generated
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	ns	
			400 kHz mode	TCY/2 (BRG + 1)	—	ns	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	ns	
IM40	TAA:SCL	Output Valid from Clock	100 kHz mode	—	3500	ns	
			400 kHz mode	—	1000	ns	
			1 MHz mode(2)	—	400	ns	
IM45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
			1 MHz mode(2)	0.5	—	µs	
IM50	CB	Bus Capacitive Loading		—	400	pF	
IM51	TPGD	Pulse Gobbler Delay		65	390	ns	See **Note 3**

Note 1: BRG is the value of the I2C™ Baud Rate Generator. Refer to **"Inter-Integrated Circuit (I2C™)"** (DS70195) in the "*dsPIC33/PIC24 Family Reference Manual*". Please see the Microchip web site for the latest "*dsPIC33/PIC24 Family Reference Manual*" sections.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: Typical value for this parameter is 130 ns.

27.0 HIGH-TEMPERATURE ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family electrical characteristics for devices operating in an ambient temperature range of -40°C to +150°C.

The specifications between -40°C to +150°C are identical to those shown in **Section 26.0 "Electrical Characteristics"** for operation between -40°C to +125°C, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes: High temperature. For example, Parameter DC10 in **Section 26.0 "Electrical Characteristics"** is the Industrial and Extended temperature equivalent of HDC10.

Absolute maximum ratings for the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 high-temperature devices are listed below. Exposure to these maximum rating conditions for extended periods can affect device reliability. Functional operation of the device at these or any other conditions, above the parameters indicated in the operation listings of this specification, is not implied.

Absolute Maximum Ratings(1)

Ambient temperature under bias(3) ..... -40°C to +150°C
Storage temperature ..... -65°C to +160°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +4.0V
Voltage on any pin that is not 5V tolerant with respect to V_{SS}(4) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on any 5V tolerant pin with respect to V_{SS} when V_{DD} < 3.0V(4) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on any 5V tolerant pin with respect to V_{SS} when $V_{DD} \geq$ 3.0V(4) ..... -0.3V to 5.6V
Maximum current out of V_{SS} pin ..... 300 mA
Maximum current into V_{DD} pin(2) ..... 250 mA
Maximum junction temperature ..... +155°C
Maximum current sourced/sunk by any 4x I/O pin ..... 4 mA
Maximum current sourced/sunk by any 8x I/O pin ..... 8 mA
Maximum current sunk by all ports combined ..... 80 mA
Maximum current sourced by all ports combined(2) ..... 80 mA

Note 1: Stresses above those listed under "Absolute Maximum Ratings" can cause permanent damage to the device. This is a stress rating only and functional operation of the device at those, or any other conditions above those indicated in the operation listings of this specification, is not implied. Exposure to maximum rating conditions for extended periods can affect device reliability.

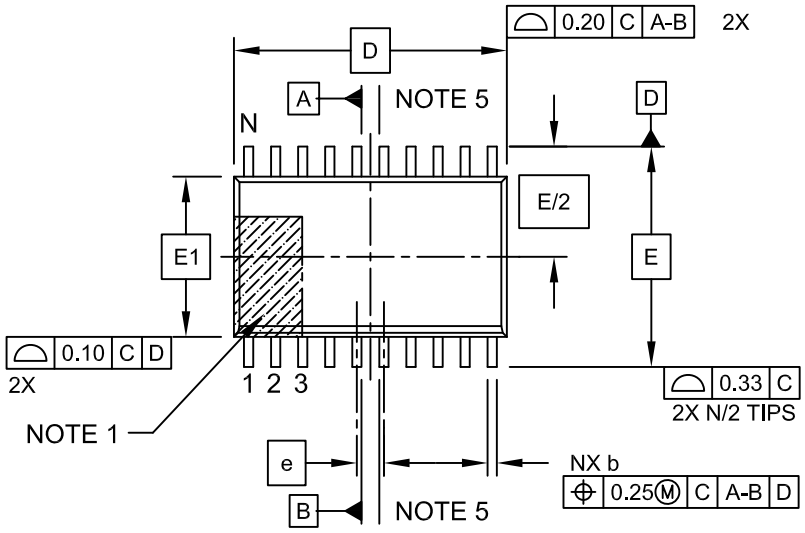
2: Maximum allowable current is a function of device maximum power dissipation (see Table 27-2).

3: AEC-Q100 reliability testing for devices intended to operate at +150°C is 1,000 hours. Any design in which the total operating time from +125°C to +150°C will be greater than 1,000 hours is not warranted without prior written approval from Microchip Technology Inc.

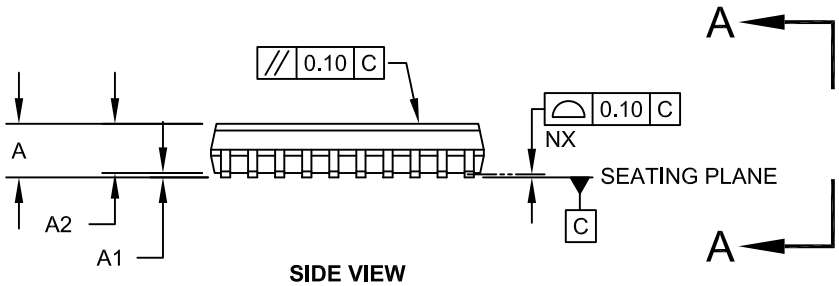
4: Refer to the **"Pin Diagrams"** section for 5V tolerant pins.

20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

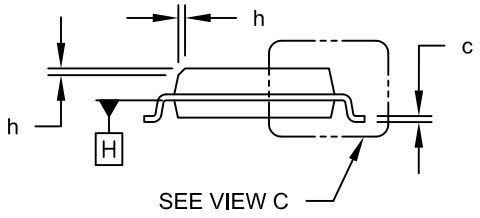
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW

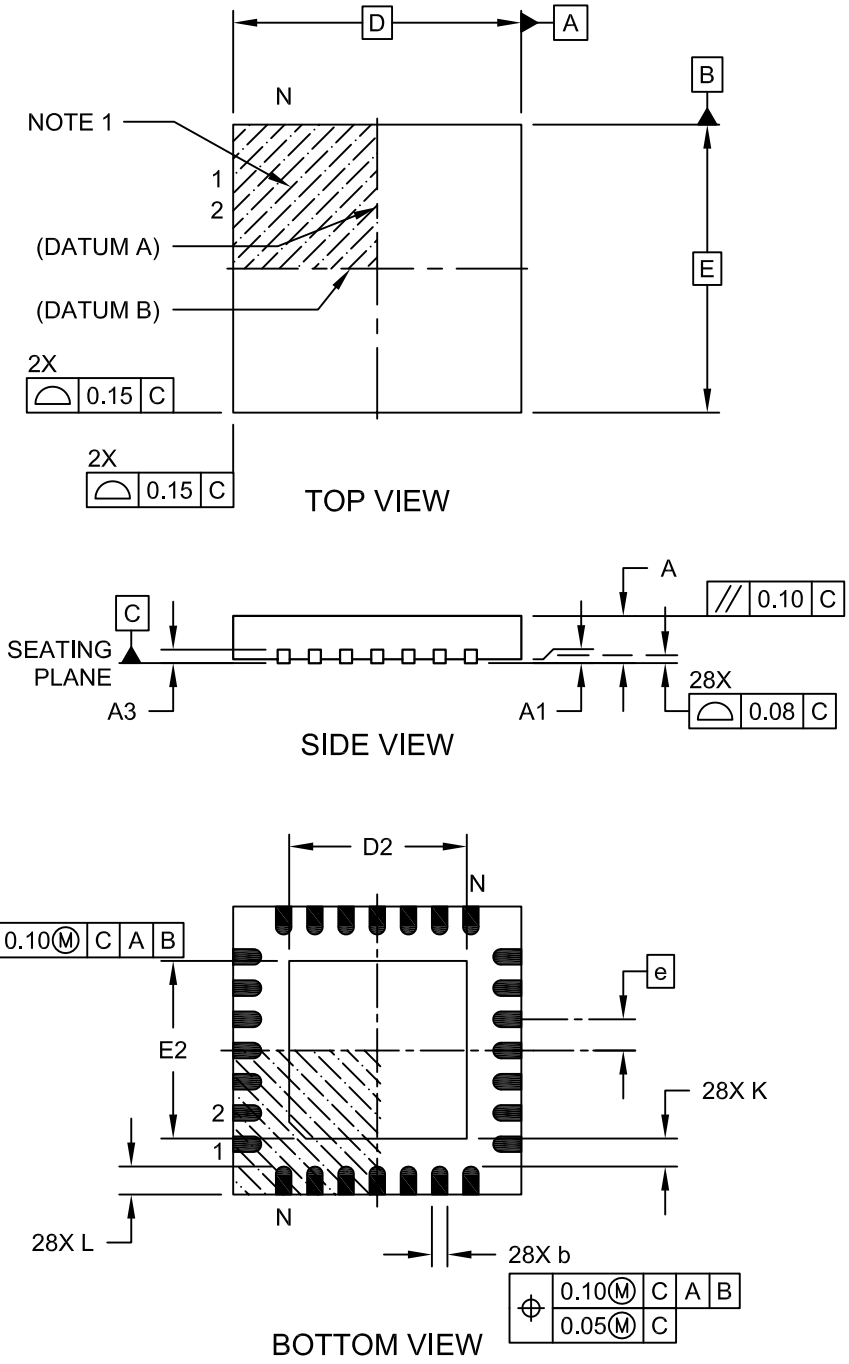


VIEW A-A

Microchip Technology Drawing C04-094C Sheet 1 of 2

28-Lead Plastic Quad Flat, No Lead Package (ML) - 6x6 mm Body [QFN]
With 0.55 mm Terminal Length

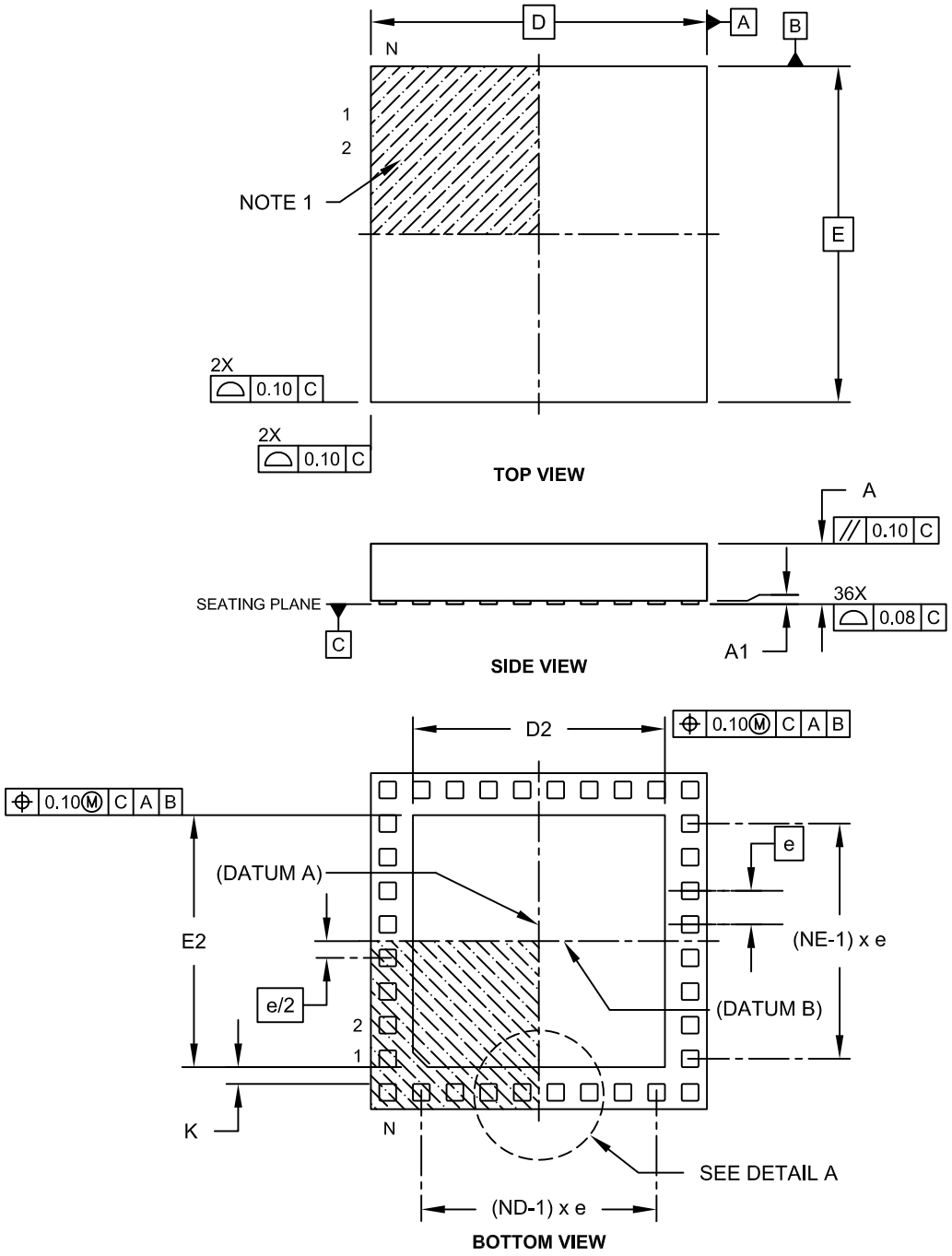
Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-105C Sheet 1 of 2

36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



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NOTES: